

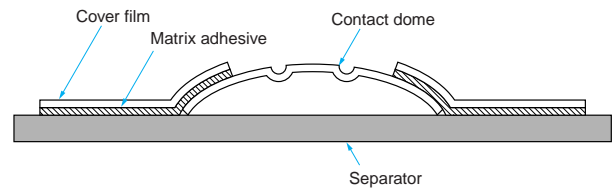
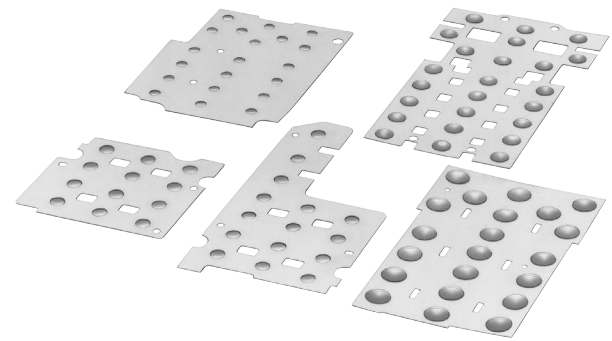
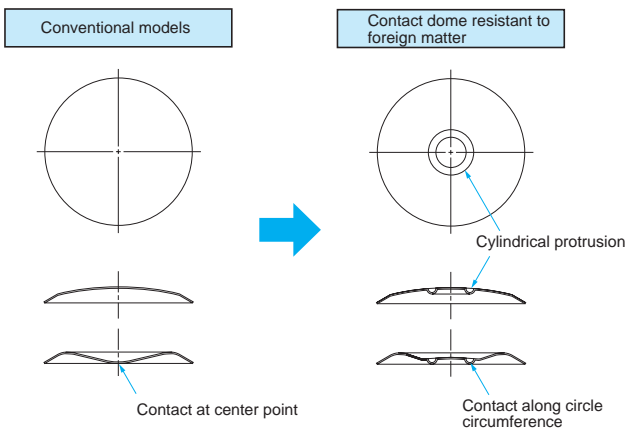
Ultra-low Profile Dome Array

B3DA

Ultra-low Profile Dome Array with Dust-Proof Construction and Crisp Clicking Action

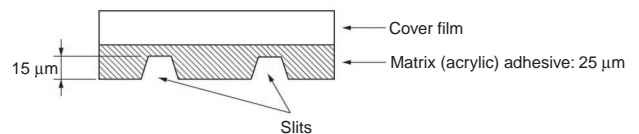
- Attach directly to PCB to make tactile switch.
- Matrix adhesive used to create highly dust-proof construction with good ventilation.
- Lower profile, lighter weight, and crisp clicking action achieved using stainless steel contact dome.
- OMRON's unique circular contact action ensures a high level of resistance to foreign matter.
- Can be designed and produced according to user specifications (e.g., external dimensions or key lay-out).

■ Structure



Matrix Adhesive

This adhesive has grid-shaped slits for ventilation with the structure shown below. The height of the slits is 15 micrometers ensuring both ventilation and dust-proofing.



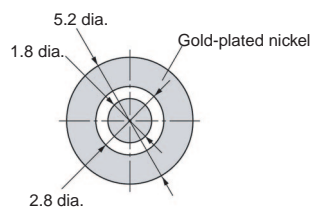
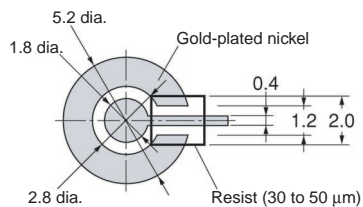
■ Contact Dome Specifications

Item	Specification
Diameter	4-mm dia. and 5-mm dia. models available
Operating force (OF)	1.57 \pm 0.49 N
Release force (RF)	0.2 N min.
Pretravel (PT)	0.2 \pm 0.1 mm
Thickness	0.25 \pm 0.1 mm
Life expectancy	4-mm dia.: 500,000 operations min. 5-mm dia.: 1,000,000 operations min.
Ambient operating temperature	-40 to 80°C
Ambient storage temperature	-40 to 85°C
Material	Stainless steel
Plating	Unplated, silver

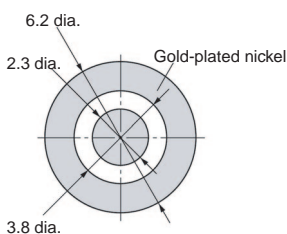
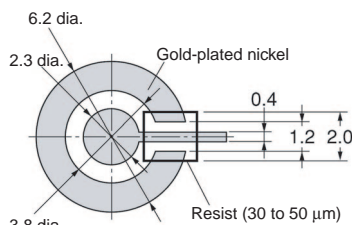
Contact dome specifications not shown in this table are also available.

■ Recommended Contact Form on PCB

4-mm Diameter Contact Dome

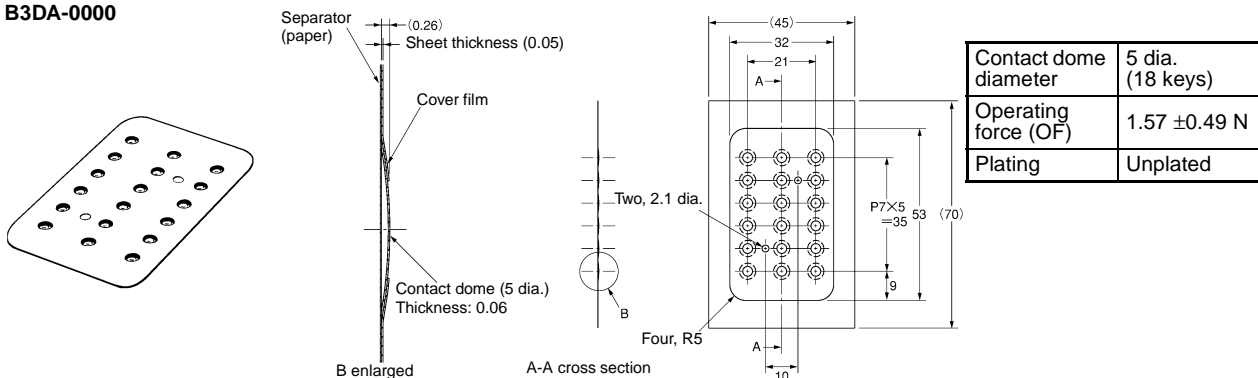


5-mm Diameter Contact Dome

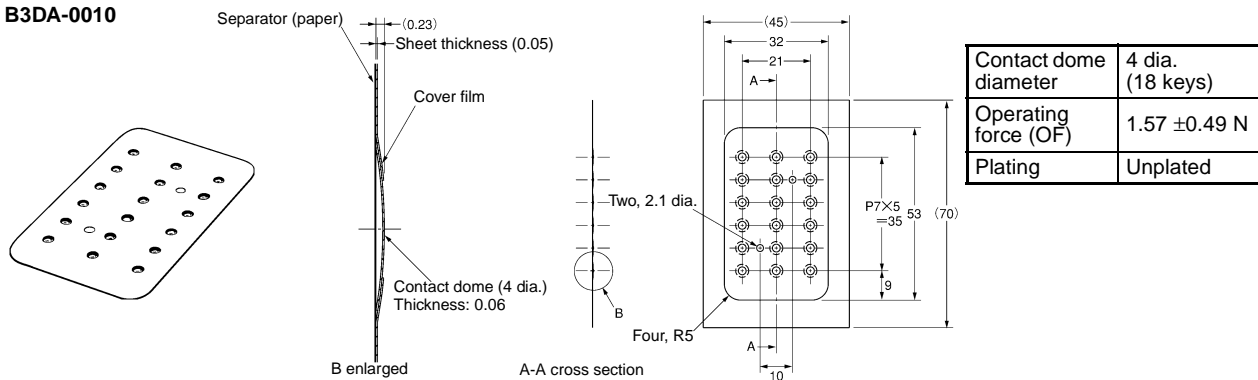


Sample for Reference

B3DA-0000



B3DA-0010



ALL DIMENSIONS SHOWN ARE IN MILLIMETERS.
 To convert millimeters into inches, multiply by 0.03937. To convert grams into ounces, multiply by 0.03527.

In the interest of product improvement, specifications are subject to change without notice.